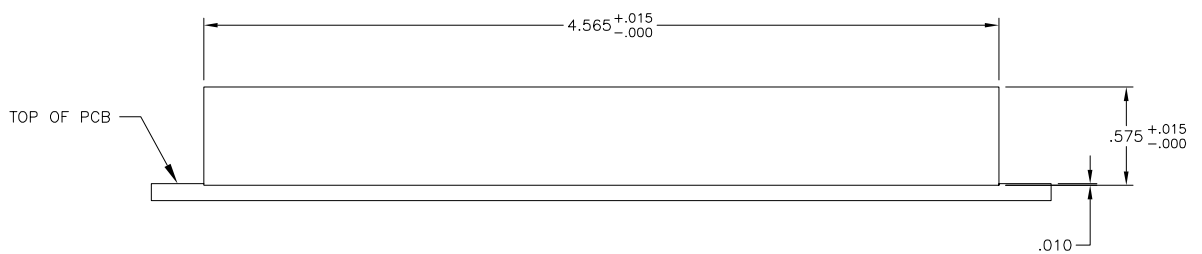
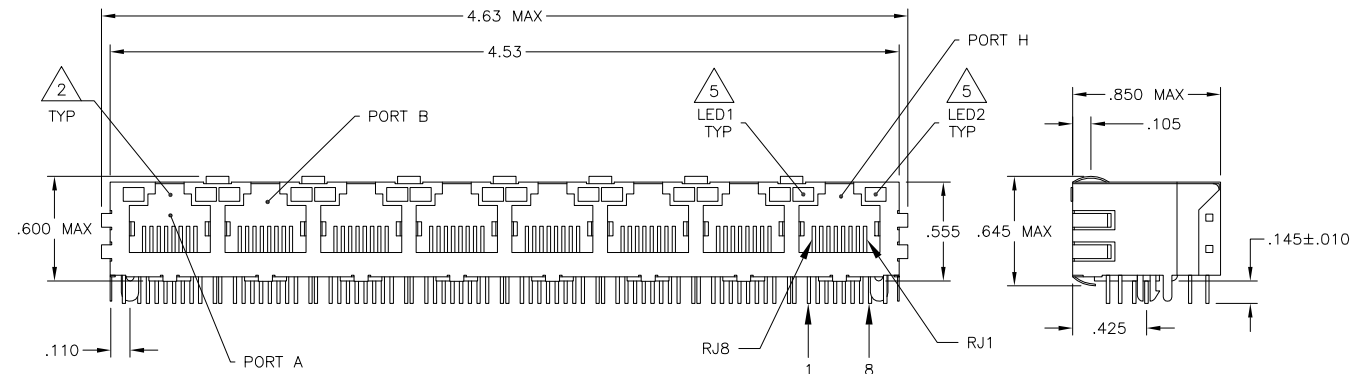
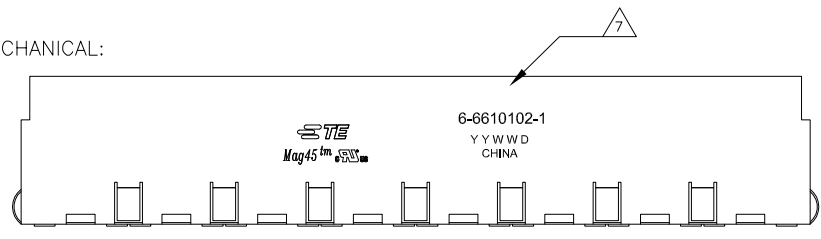


LOC	AA	DIST	22	REVISIONS			
REV	PER	DESCRIPTION	DATE	BY	APP'D		
D		ECO-09-025671	16NOV2009	QL	LR		
E		ECO-11-013353	20MAY2011	EL	LR		

MECHANICAL:



1X8 SUGGESTED PANEL CUTOUT

- 1. HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 SHIELD - 0.10" THICK C28800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE. 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.20" X 0.20" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- 2. RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- 3. MAGNETICS
 IMPEDANCE: 100 OHMS
 TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
 OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mA DC BIAS FROM 0°C TO 70°C, TX AND RX
 PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30dB) MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20*LOG(f/50dB) MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.
- 4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
- 5. IF THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA.
 LED COLOR : DOMINANT WAVELENGTH (LD): GREEN 568 nm TYP. @ VF=5V
 FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V
- 6. INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL AND SUPPORT OR AUTO-MDI/MDIX.
- 7. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
- 8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS. PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

GREEN	GREEN	6-6610102-1
LED1	LED2	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DESIGNED BY: A. FERNANDEZ (10MAR2009)	DATE: 10MAR2009	NAME: A. FERNANDEZ
DRAWN BY: D. FAROLE (10MAR2009)	DATE: 10MAR2009	NAME: D. FAROLE
APPROVED BY: D. FAROLE (10MAR2009)	DATE: 10MAR2009	NAME: D. FAROLE

TE Connectivity

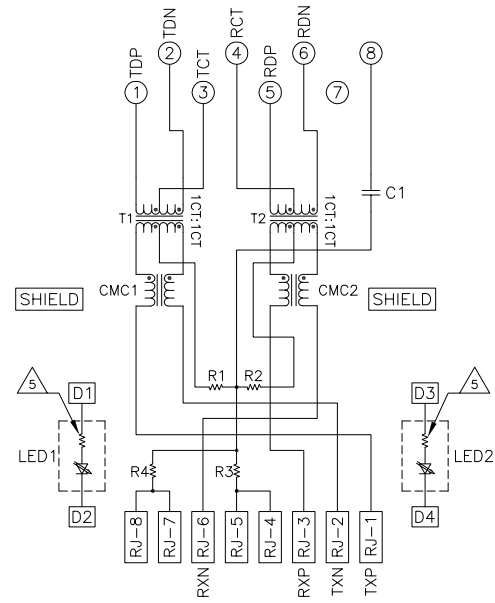
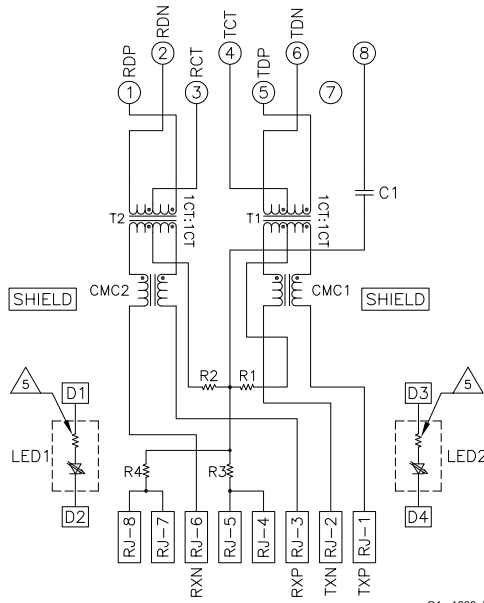
1X8 MA645(TW) MODULAR JACK, 7K2 SCHEMATIC, 726K2 SERIES CIRCUIT, DECOUPLING CAPACITOR, SHIELDED, WITH RESISTOR LEADS

SIZE	A1	DATE CODE	00779	DRAWING NO	C-6610102
SCALE	2:1	SHEET	1	OF	2
REV	F				

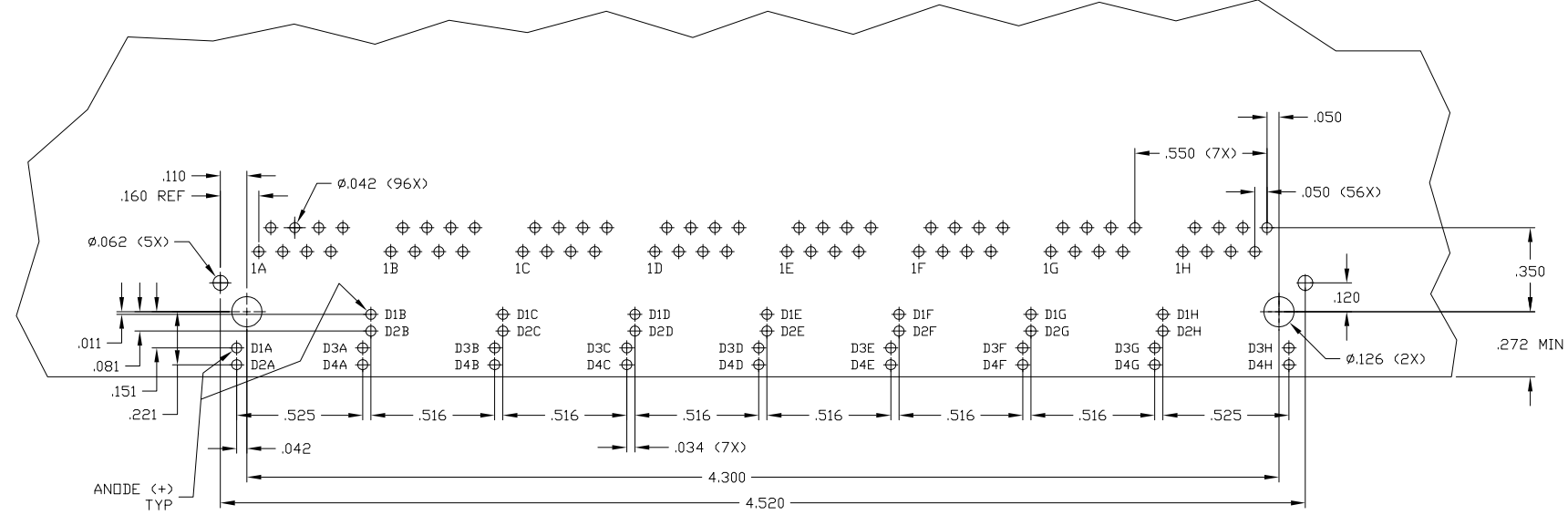
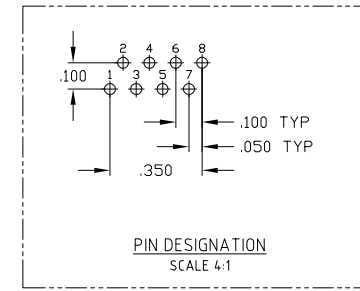
LOC	REV	DATE	DESCRIPTION	BY	APP'D
AA	22		SEE SHEET 1		

726K2 SERIES MAGNETIC CIRCUIT
PORTS 1,3,5,7

726K2 SERIES MAGNETIC CIRCUIT
PORTS 2,4,6,8



C1 = 1000pF, 2kV CAPACITOR
R1-R4 = 75 OHMS, 1/16 W RESISTORS



SUGGESTED PCB LAYOUT
(Component Side)
SCALE 4:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	DATE	DESCRIPTION
DRAWN BY: A. FERNANDEZ-RODRIGUEZ		1	10MAR2003	1X8 MA645(TW) MODULAR JACK, 7K2 SCHEMATIC
CHECKED BY: D. FAROLE		2	10MAR2003	726K2 SERIES CIRCUIT, DECOUPLING CAPACITOR, SHIELDED, WITH RESISTOR LEADS
APPROVED BY: D. FAROLE		3	10MAR2003	
DRAWN BY: D. FAROLE		4	10MAR2003	
CHECKED BY: D. FAROLE				
APPROVED BY: D. FAROLE				
MATERIAL: -		SIZE	DATE CODE	DRAWING NO.
FINISH: -		A1	00779	C=6610102
WEIGHT: -		CUSTOMER DRAWING	SCALE	SHEET
			2:1	2 of 2

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)